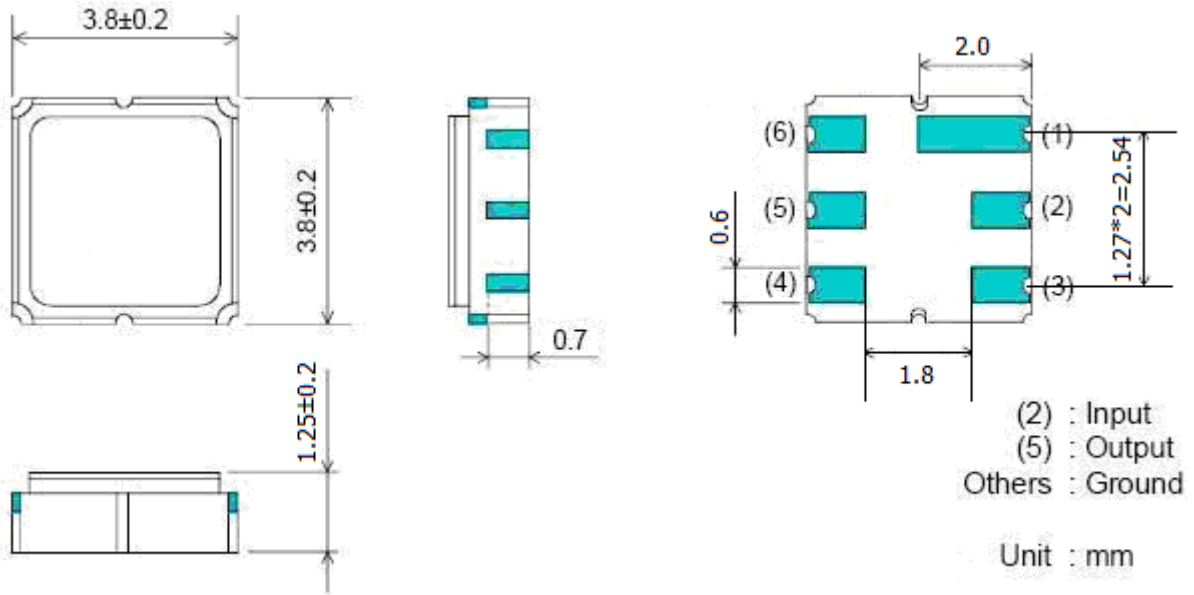


1. Package Dimension



2. Maximum Rating

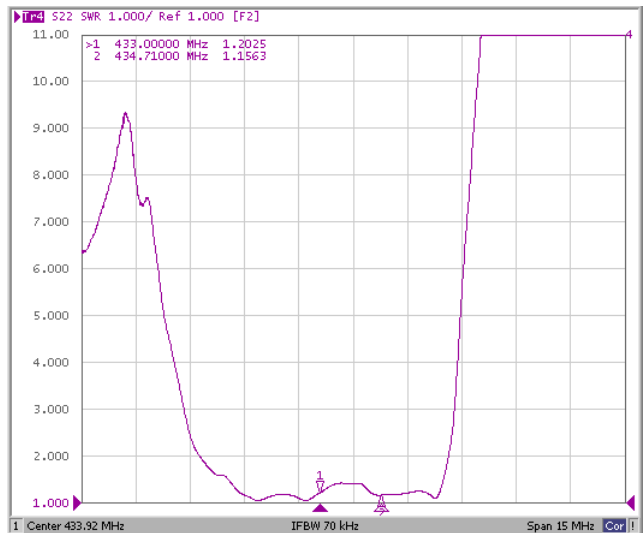
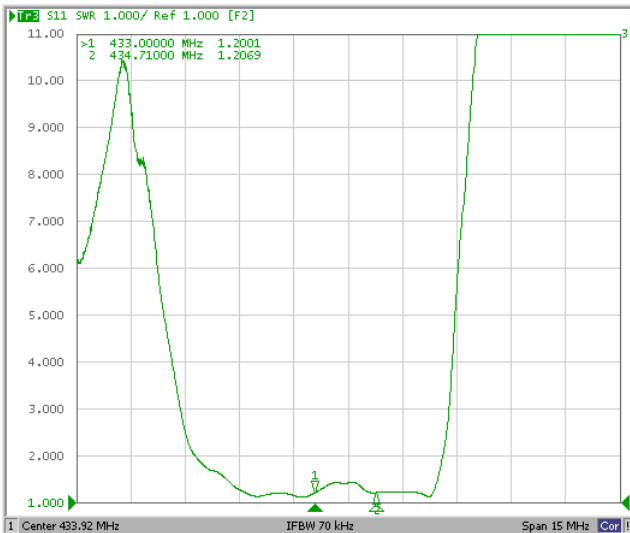
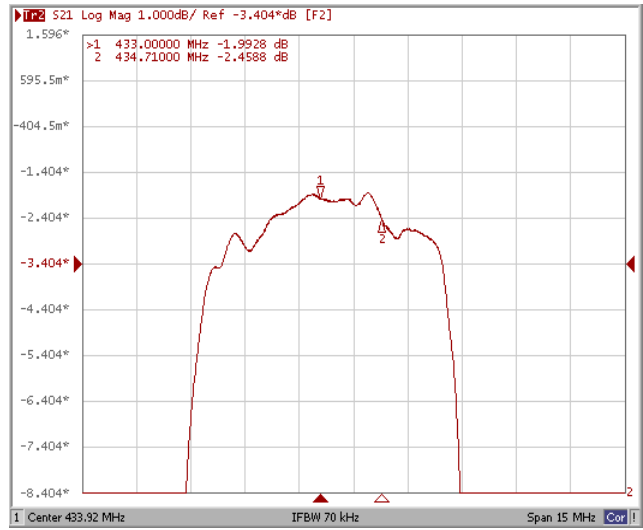
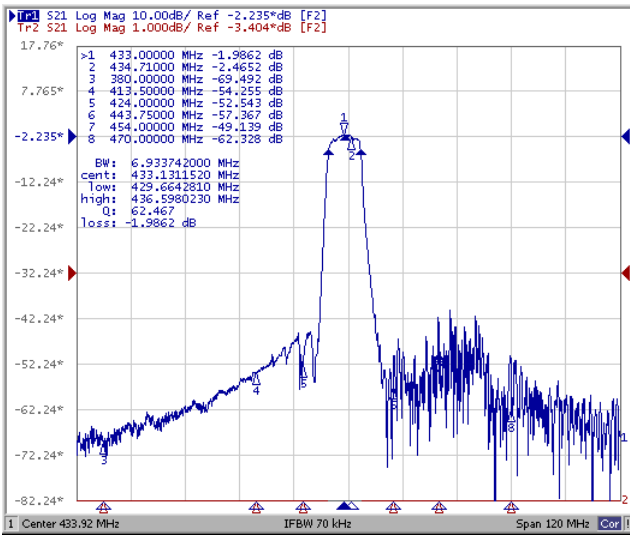
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
RF Power	20dBm

3.1 Electronic Characteristics

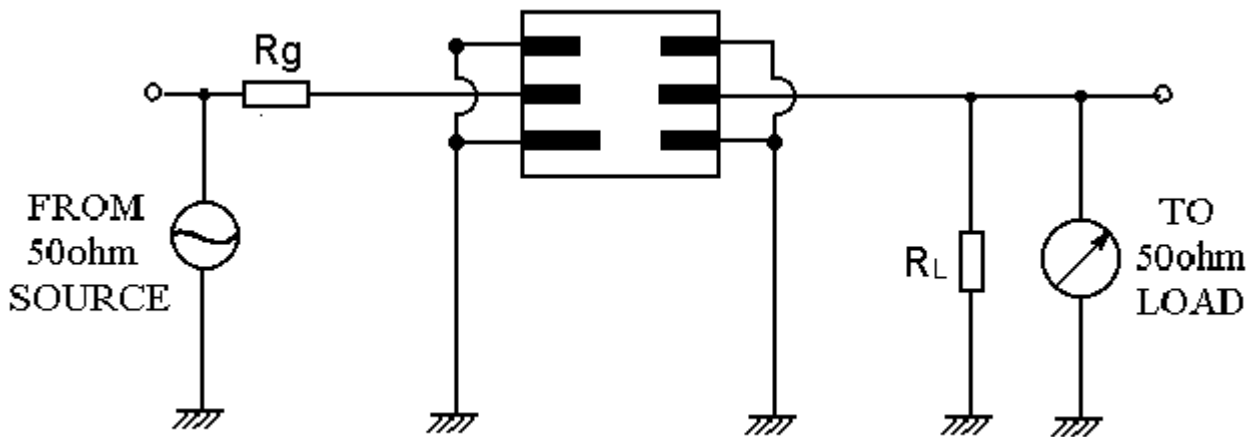
	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	433.92	-
Insertion Loss (433.00~434.71 MHz)	dB		2.5	3.2
Amplitude Ripple (433.00~434.71 MHz)	dB		0.8	2.0
VSWR(433.00~434.71 MHz)			1.5	
Relative Attenuation				
DC ~ 380 MHz	dB	55	65	-
380 ~ 413.5 MHz		45	52	
413.5 ~ 424 MHz		40	43	
443.75 ~ 470 MHz		35	38	
470 ~ 650 MHz		43	48	
650 ~ 1000 MHz		40	50	
Input/Output Impedance	Ohms		50	

SAW Filter

3.2 Frequency Characteristics



4. Test Circuit



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.1.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.1.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C \pm 10°C for 10 \pm 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.1.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C \pm 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 3.1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Packing

7.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

SAW Filter

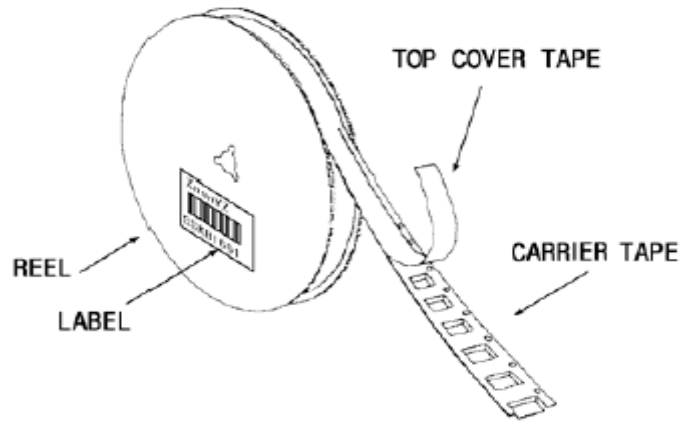
7.2 Reeling Quantity

1000 pcs/reel 7"

3000 pcs/reel 13"

7.3 Taping Structure

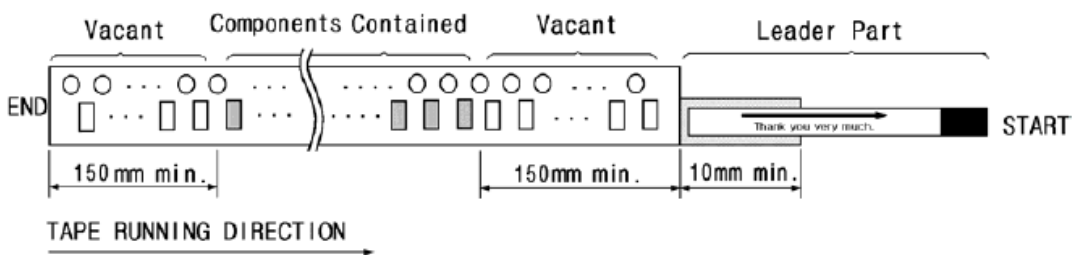
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



8. TAPE SPECIFICATIONS

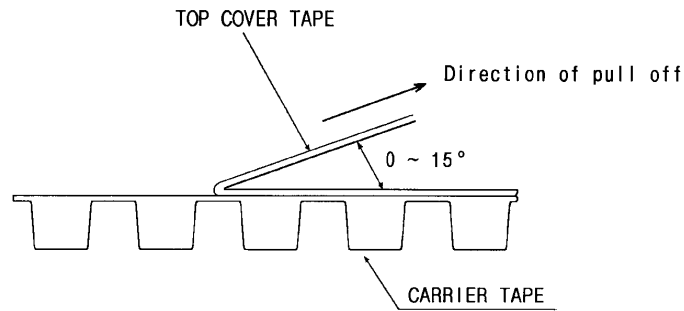
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

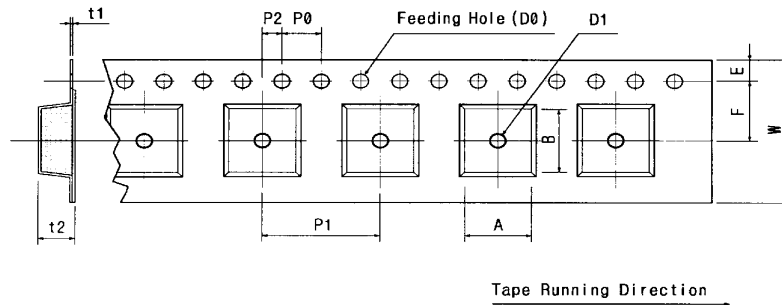
(1) pull off angle: 0~15°

(2) speed: 300mm/min.

(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

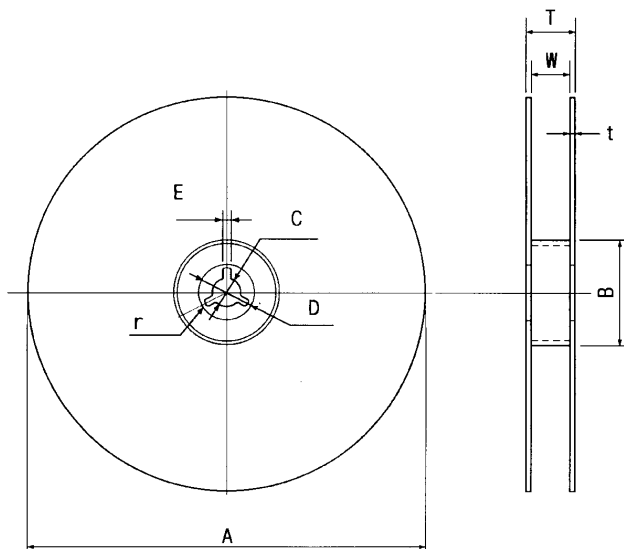


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00	5.50	1.75	4.00	4.00	2.00	$\varnothing 1.50$	$\varnothing 1.5$	0.31	1.30	3.4	3.4
± 0.30	± 0.10	± 0.10	± 0.10	± 0.10	± 0.10		± 0.25	± 0.05	± 0.10	MAX.	MAX.

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
$\varnothing 330$	$\varnothing 100$	$\varnothing 13$	$\varnothing 21$	2	13	3	1.0
± 1.0	± 0.5	± 0.5	± 0.8	± 0.5	± 0.3	max.	max.